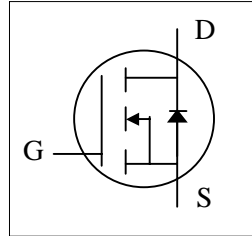


- ▼ Simple Drive Requirement
- ▼ 100% R<sub>g</sub> & UIS Test
- ▼ Ultra Low On-resistance
- ▼ RoHS Compliant & Halogen-Free

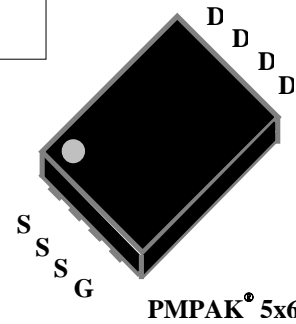


$BV_{DSS}$	60V
$R_{DS(ON)}$	1.7m $\Omega$

### Description

XP6NA1R7C series are innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The PMPAK<sup>®</sup> 5x6 package is special for DC-DC converters application and the foot print is compatible with SO-8 with backside heat sink and lower profile.



### Absolute Maximum Ratings @T<sub>j</sub>=25°C (unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	+20	V
$I_D @ T_C=25^\circ C$	Drain Current, $V_{GS} @ 10V^4$ (Silicon Limited)	190	A
$I_D @ T_C=25^\circ C$	Drain Current, $V_{GS} @ 10V^4$	100	A
$I_D @ T_A=25^\circ C$	Drain Current, $V_{GS} @ 10V^3$	41.6	A
$I_D @ T_A=70^\circ C$	Drain Current, $V_{GS} @ 10V^3$	33.3	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	350	A
$P_D @ T_C=25^\circ C$	Total Power Dissipation	104	W
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>3</sup>	5	W
$E_{AS}$	Single Pulse Avalanche Energy <sup>5</sup>	180	mJ
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Value	Unit
Rthj-c	Maximum Thermal Resistance, Junction-case	1.2	°C/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient <sup>3</sup>	25	°C/W

**Electrical Characteristics @T<sub>j</sub>=25°C(unless otherwise specified)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60	-	-	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	-	1.7	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	2	-	4	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A	-	70	-	S
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V	-	-	25	uA
I <sub>GSS</sub>	Gate-Source Leakage	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±0.1	uA
Q <sub>g</sub>	Total Gate Charge	I <sub>D</sub> =20A	-	100	160	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =30V	-	30	-	nC
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	V <sub>GS</sub> =10V	-	27	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =30V	-	22	-	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =30A	-	65	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	R <sub>G</sub> =1.6Ω	-	40	-	ns
t <sub>f</sub>	Fall Time	V <sub>GS</sub> =10V	-	16	-	ns
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V	-	5500	8800	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =50V	-	1000	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	20	-	pF
R <sub>g</sub>	Gate Resistance	f=1.0MHz	-	1.2	2.4	Ω

**Source-Drain Diode**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V <sub>SD</sub>	Forward On Voltage <sup>2</sup>	I <sub>S</sub> =20A, V <sub>GS</sub> =0V	-	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> =20A, V <sub>GS</sub> =0V,	-	62	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI/dt=100A/μs	-	72	-	nC

**Notes:**

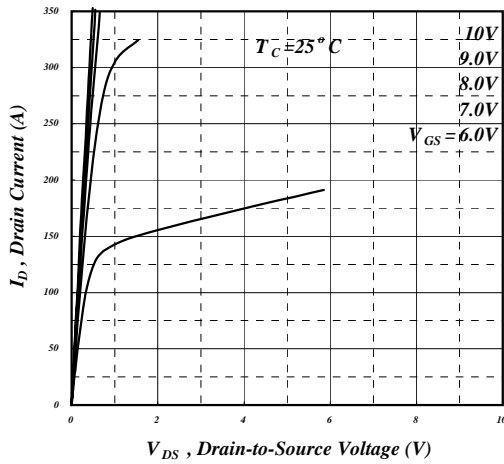
- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board, t ≤10sec; 60°C/W at steady state.
- 4.Package limitation current is 100A .
- 5.Starting T<sub>j</sub>=25°C , V<sub>DD</sub>=30V , L=0.1mH , R<sub>G</sub>=25Ω , V<sub>GS</sub>=10V

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

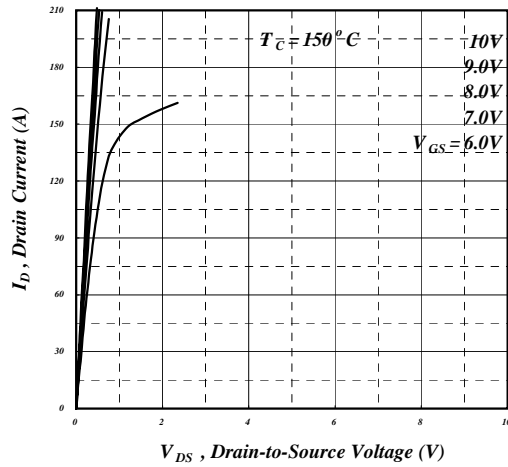
USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT, AUTOMOTIVE OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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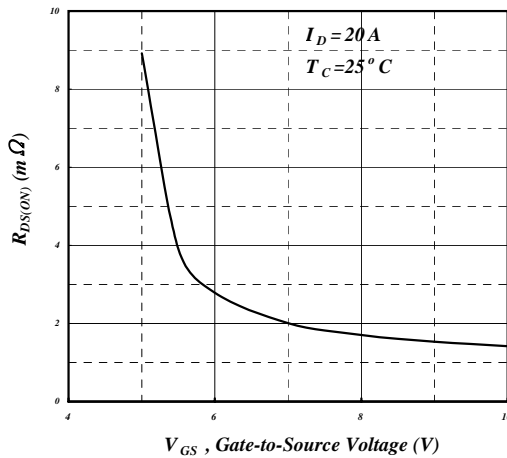
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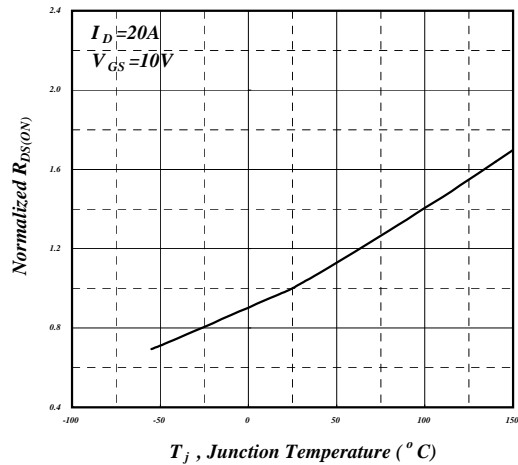
**Fig 1. Typical Output Characteristics**



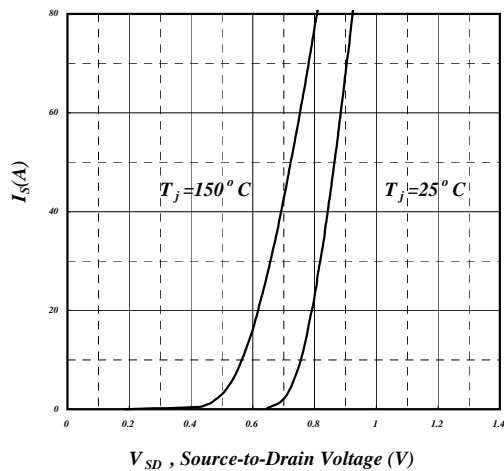
**Fig 2. Typical Output Characteristics**



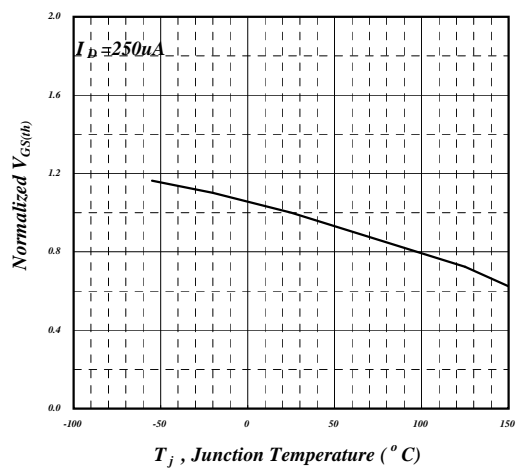
**Fig 3. On-Resistance v.s. Gate Voltage**



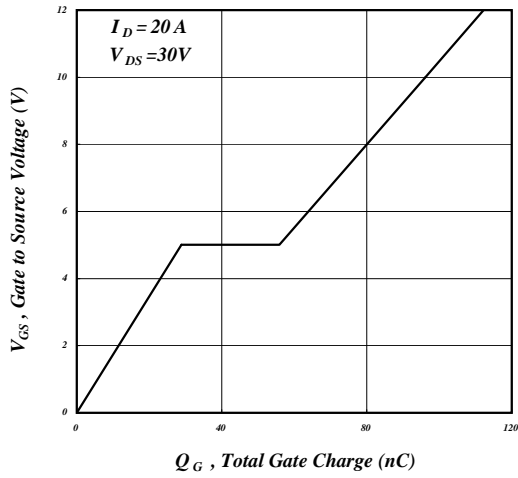
**Fig 4. Normalized On-Resistance v.s. Junction Temperature**



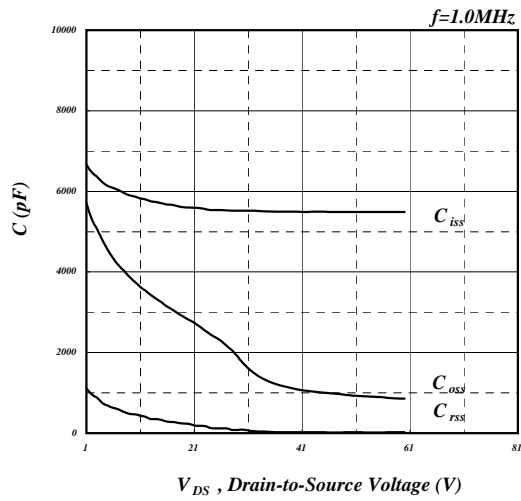
**Fig 5. Forward Characteristic of Reverse Diode**



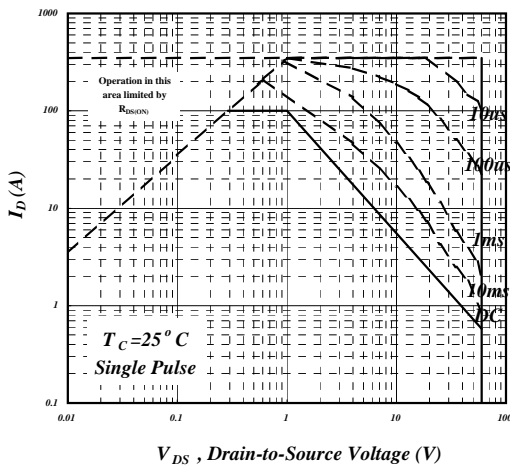
**Fig 6. Gate Threshold Voltage v.s. Junction Temperature**



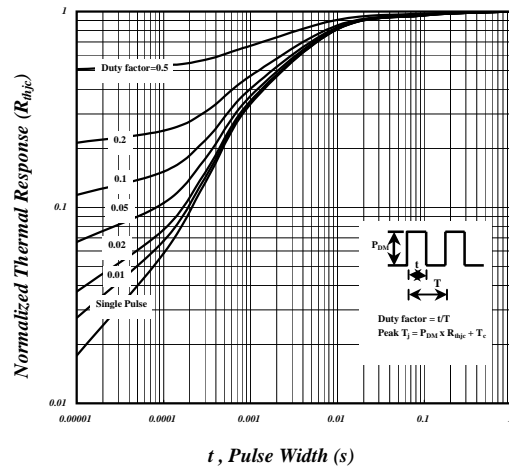
**Fig 7. Gate Charge Characteristics**



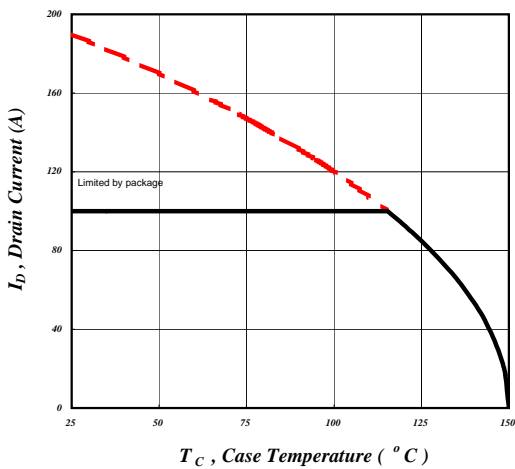
**Fig 8. Typical Capacitance Characteristics**



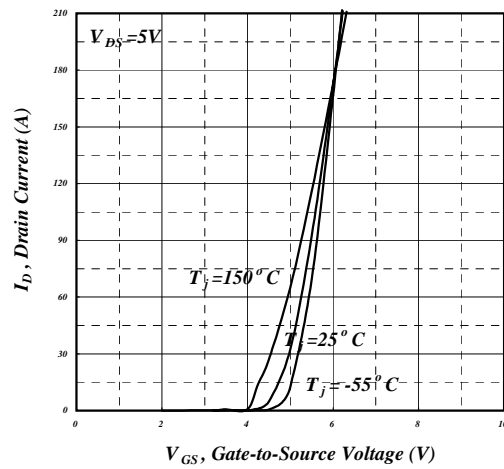
**Fig 9. Maximum Safe Operating Area**



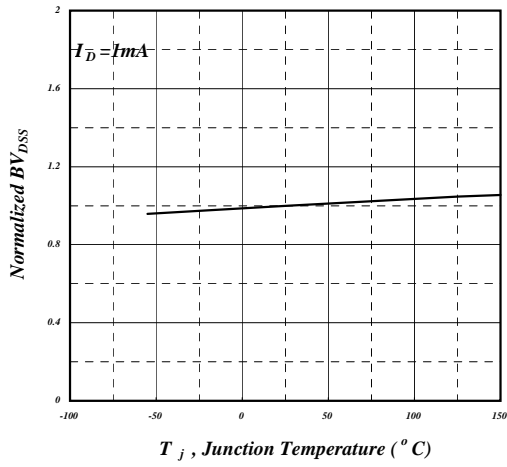
**Fig 10. Effective Transient Thermal Impedance**



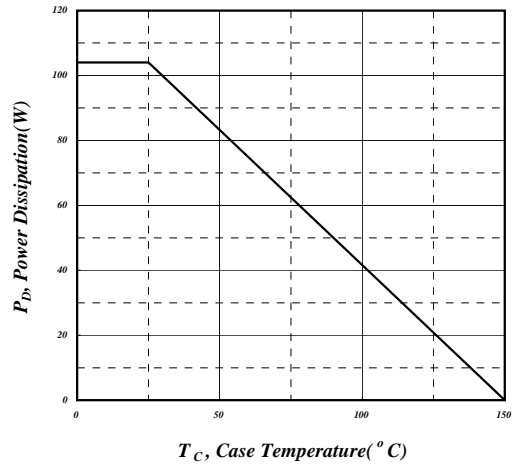
**Fig 11. Drain Current v.s. Case Temperature**



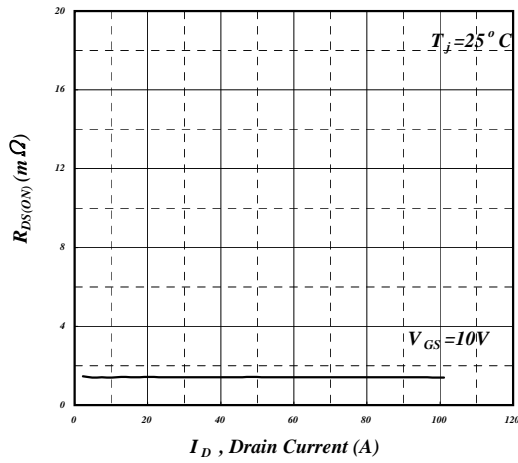
**Fig 12. Transfer Characteristics**



**Fig 13. Normalized  $BV_{DSS}$  v.s. Junction Temperature**



**Fig 14. Total Power Dissipation**



**Fig 15. Typ. Drain-Source on State Resistance**

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**MARKING INFORMATION**

